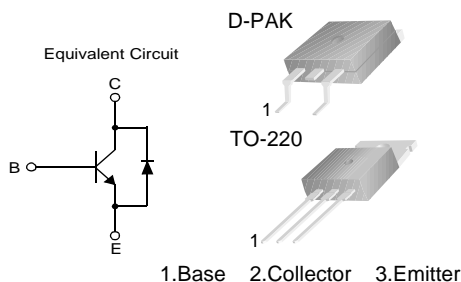


## KSC5402D/KSC5402DT

### High Voltage High Speed Power Switch Application

- Wide Safe Operating Area
- Built-in Free Wheeling Diode
- Suitable for Electronic Ballast Application
- Small Variance in Storage Time
- Two Package Choices; D-PAK or TO-220



### NPN Silicon Transistor Planar Silicon Transistor

#### Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
$V_{CBO}$	Collector-Base Voltage	1000	V
$V_{CEO}$	Collector-Emitter Voltage	450	V
$V_{EBO}$	Emitter-Base Voltage	12	V
$I_C$	Collector Current (DC)	2	A
$I_{CP}$	*Collector Current (Pulse)	5	A
$I_B$	Base Current (DC)	1	A
$I_{BP}$	*Base Current (Pulse)	2	A
$P_C$	Power Dissipation( $T_C=25^\circ\text{C}$ ) : D-PAK * : TO-220	30 50	W
$T_J$	Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature	- 65 ~ 150	$^\circ\text{C}$

\* Pulse Test: Pulse Width=5ms, Duty Cycle  $\leq$  10%

#### Thermal Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Characteristics	Rating		Unit	
		TO-220	D-PAK		
$R_{\theta jc}$	Thermal Resistance	Junction to Case	2.5	4.17 *	$^\circ\text{C/W}$
$R_{\theta ja}$		Junction to Ambient	62.5	50	
$T_L$	Maximum Lead Temperature for Soldering Purpose ; 1/8" from Case for 5 Seconds	270	270	$^\circ\text{C}$	

\* Mounted on 1" square PCB (FR4 ro G-10 Material)

**Electrical Characteristics**  $T_C=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
$BV_{CBO}$	Collector-Base Breakdown Voltage	$I_C=1\text{mA}, I_E=0$	1000	1090		V
$BV_{CEO}$	Collector-Emitter Breakdown Voltage	$I_C=5\text{mA}, I_B=0$	450	525		V
$BV_{EBO}$	Emitter-Base Breakdown Voltage	$I_E=1\text{mA}, I_C=0$	12	14		V
$I_{CES}$	Collector Cut-off Current	$V_{CES}=1000\text{V}, I_{EB}=0$	$T_C=25^\circ\text{C}$	0.03	100	$\mu\text{A}$
			$T_C=125^\circ\text{C}$	1.2	500	
$I_{CEO}$	Collector Cut-off Current	$V_{CE}=450\text{V}, V_B=0$	$T_C=25^\circ\text{C}$	0.3	100	$\mu\text{A}$
			$T_C=125^\circ\text{C}$	15	500	
$I_{EBO}$	Emitter Cut-off Current	$V_{EB}=10\text{V}, I_C=0$		0.01	100	$\mu\text{A}$
$h_{FE}$	DC Current Gain	$V_{CE}=1\text{V}, I_C=0.4\text{A}$	$T_C=25^\circ\text{C}$	14	29	
			$T_C=125^\circ\text{C}$	8	17	
		$V_{CE}=1\text{V}, I_C=1\text{A}$	$T_C=25^\circ\text{C}$	6	9	
			$T_C=125^\circ\text{C}$	4	6	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=0.4, I_B=0.04\text{A}$	$T_C=25^\circ\text{C}$	0.25	0.6	
			$T_C=125^\circ\text{C}$	0.4	1.0	
		$I_C=1\text{A}, I_B=0.2\text{A}$	$T_C=25^\circ\text{C}$	0.3	0.75	V
			$T_C=125^\circ\text{C}$	0.65	1.2	V
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C=0.4\text{A}, I_B=0.04\text{A}$	$T_C=25^\circ\text{C}$	0.78	1.0	V
			$T_C=125^\circ\text{C}$	0.65	0.9	V
		$I_C=1\text{A}, I_B=0.2\text{A}$	$T_C=25^\circ\text{C}$	0.85	1.1	V
			$T_C=125^\circ\text{C}$	0.75	1.0	V
$C_{ib}$	Input Capacitance	$V_{EB}=8\text{V}, I_C=0, f=1\text{MHz}$		330	500	pF
$C_{ob}$	Output Capacitance	$V_{CB}=10\text{V}, I_E=0, f=1\text{MHz}$		35	100	pF
$f_T$	Current Gain Bandwidth Product	$I_C=0.5\text{A}, V_{CE}=10\text{V}$		11		MHz
$V_F$	Diode Forward Voltage	$I_F=1\text{A}$	$T_C=25^\circ\text{C}$	0.86	1.5	V
			$T_C=125^\circ\text{C}$	0.75	1.2	V
		$I_F=0.2\text{A}$	$T_C=25^\circ\text{C}$	0.6		V
			$T_C=125^\circ\text{C}$	0.8	1.3	V
			$T_C=125^\circ\text{C}$	0.65		V

**Electrical Characteristics**  $T_C=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Condition	Min	Typ.	Max.	Units	
$t_{fr}$	Diode Forward Recovery Time ( $di/dt=10\text{A}/\mu\text{s}$ )	$I_F=0.2\text{A}$		540		ns	
		$I_F=0.4\text{A}$		520		ns	
		$I_F=1\text{A}$		480		ns	
$V_{CE(DSAT)}$	Dynamic Saturation Voltage	$I_C=0.4\text{A}$ , $I_{B1}=40\text{mA}$ $V_{CC}=300\text{V}$	@ $1\mu\text{s}$		7.5		V
			@ $3\mu\text{s}$		2.5		V
		$I_C=1\text{A}$ , $I_{B1}=200\text{mA}$ $V_{CC}=300$	@ $1\mu\text{s}$		11.5		V
			@ $3\mu\text{s}$		1.5		V
RESISTIVE LOAD SWITCHING (D.C $\leq 10\%$ , Pulse Width= $20\mu\text{s}$ )							
$t_{ON}$	Turn On Time	$I_C=1\text{A}$ , $I_{B1}=200\text{mA}$	$T_C=25^\circ\text{C}$		110	150	ns
			$T_C=125^\circ\text{C}$		135		ns
$t_{OFF}$	Turn Off Time	$I_{B2}=150\text{mA}$ $V_{CC}=300\text{V}$ $R_L = 300\Omega$	$T_C=25^\circ\text{C}$	0.95		1.25	$\mu\text{s}$
			$T_C=125^\circ\text{C}$		1.4		$\mu\text{s}$
INDUCTIVE LOAD SWITCHING ( $V_{CC}=15\text{V}$ )							
$t_{STG}$	Storage Time	$I_C=0.4\text{A}$ , $I_{B1}=40\text{mA}$	$T_C=25^\circ\text{C}$		0.56	0.65	$\mu\text{s}$
			$T_C=125^\circ\text{C}$		0.7		$\mu\text{s}$
$t_F$	Fall Time	$I_{B2}=200\text{mA}$ , $V_Z=300\text{V}$ $L_C=200\text{H}$	$T_C=25^\circ\text{C}$		60	175	ns
			$T_C=125^\circ\text{C}$		75		ns
$t_C$	Cross-over Time		$T_C=25^\circ\text{C}$		90	175	ns
			$T_C=125^\circ\text{C}$		90		ns
$t_{STG}$	Storage Time	$I_C=0.8\text{A}$ , $I_{B1}=160\text{mA}$	$T_C=25^\circ\text{C}$		2.75		$\mu\text{s}$
			$T_C=125^\circ\text{C}$		3		$\mu\text{s}$
$t_F$	Fall Time	$I_{B2}=160\text{mA}$ , $V_Z=300\text{V}$ $L_C=200\text{H}$	$T_C=25^\circ\text{C}$		110	175	ns
			$T_C=125^\circ\text{C}$		180		ns
$t_C$	Cross-over Time		$T_C=25^\circ\text{C}$		125	350	ns
			$T_C=125^\circ\text{C}$		185		ns
$t_{STG}$	Storage Time	$I_C=1\text{A}$ , $I_{B1}=200\text{mA}$	$T_C=25^\circ\text{C}$		1.1	1.2	$\mu\text{s}$
			$T_C=125^\circ\text{C}$		1.35		$\mu\text{s}$
$t_F$	Fall Time	$I_{B2}=500\text{mA}$ , $V_Z=300\text{V}$ $L_C=200\mu\text{H}$	$T_C=25^\circ\text{C}$		105	150	ns
			$T_C=125^\circ\text{C}$		75		ns
$t_C$	Cross-over Time		$T_C=25^\circ\text{C}$		125	150	ns
			$T_C=125^\circ\text{C}$		100		ns

# Typical Characteristics

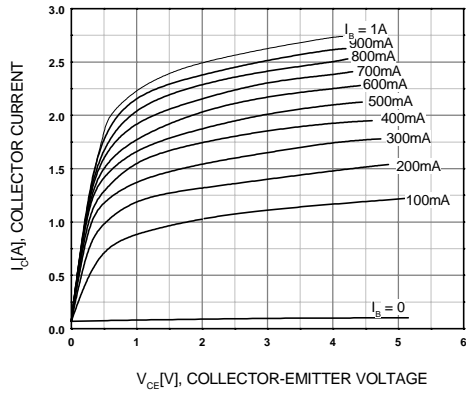


Figure 1. Static Characteristic

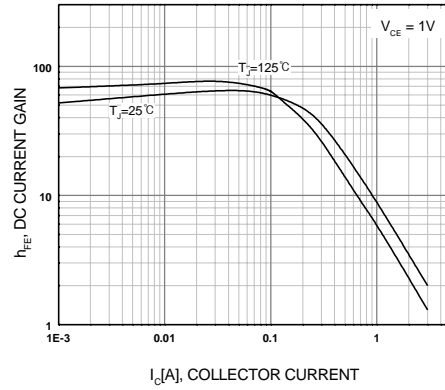


Figure 2. DC current Gain

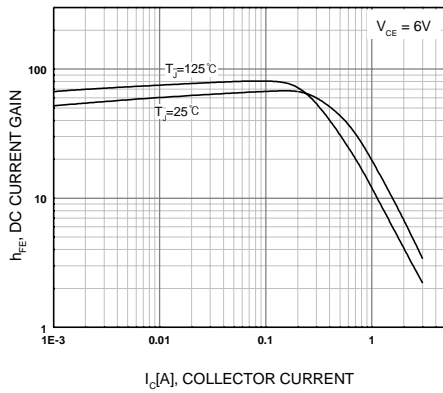


Figure 3. DC current Gain

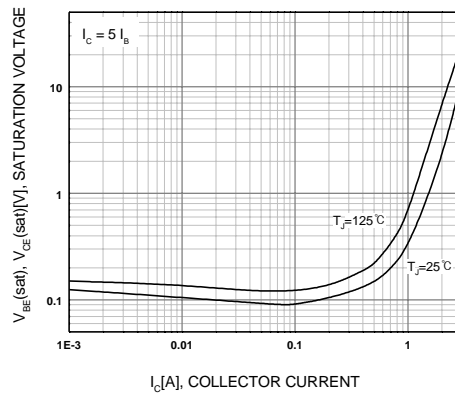


Figure 4. Collector-Emitter Saturation Voltage

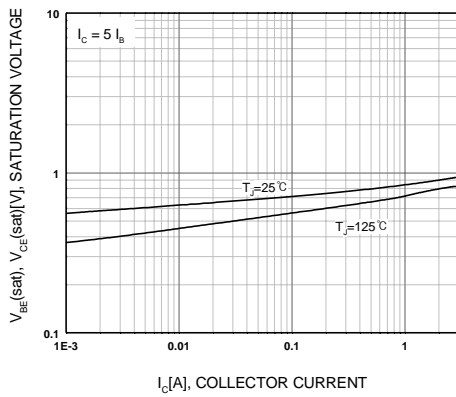


Figure 5. Base-Emitter Saturation Voltage

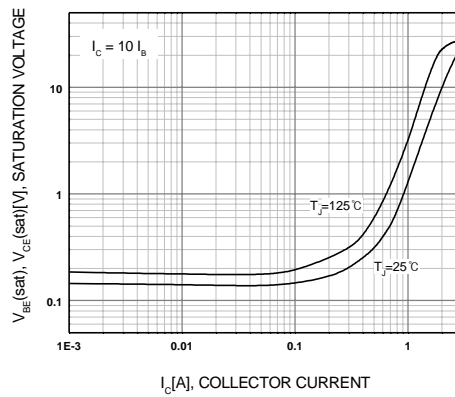


Figure 6. Collector-Emitter Saturation Voltage

Typical Characteristics (Continued)

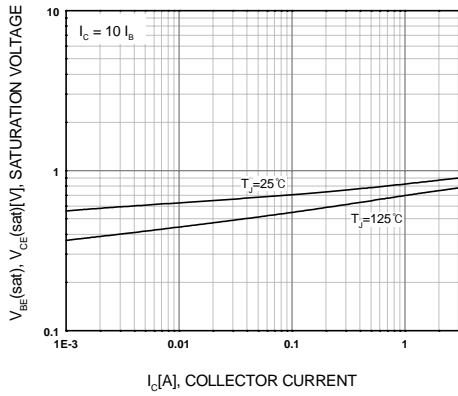


Figure 7. Base-Emitter Saturation Voltage

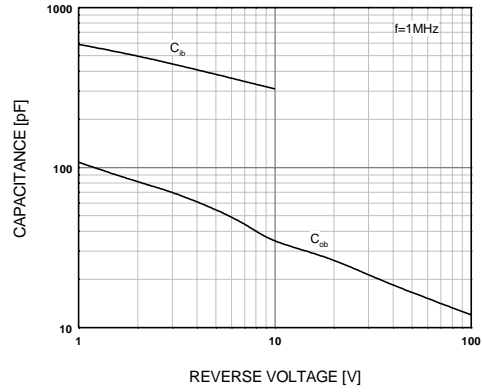


Figure 8. Collector Output Capacitance

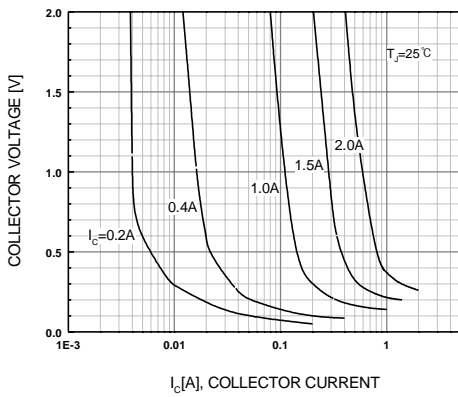


Figure 9. Typical Collector Saturation Region

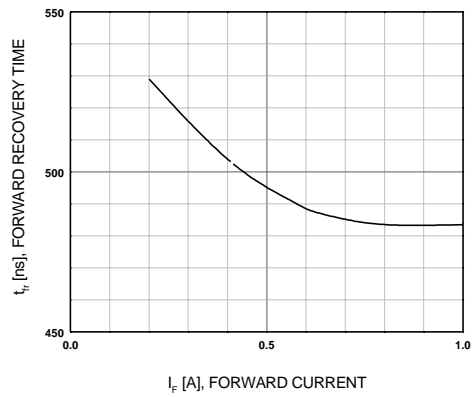


Figure 10. Forward Recovery Time

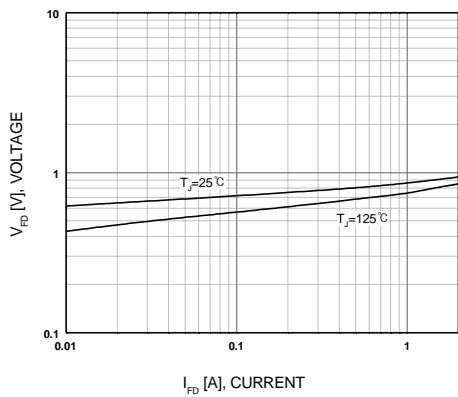


Figure 11. Diode Forward Voltage

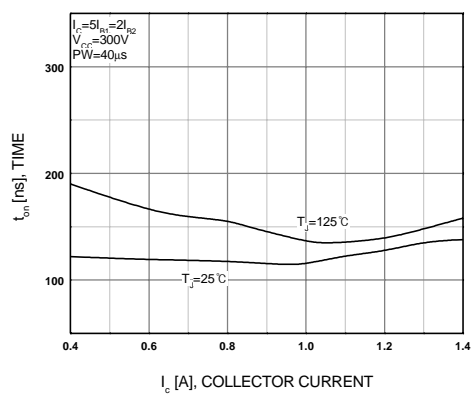


Figure 12. Resistive Switching Time,  $t_{on}$

Typical Characteristics (Continued)

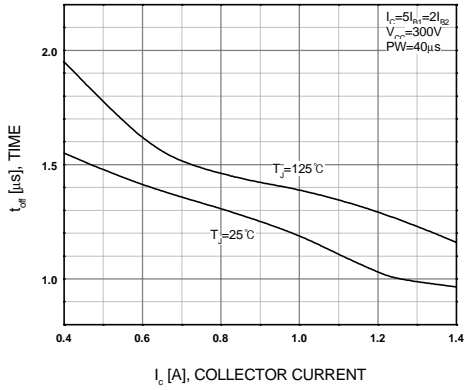


Figure 13. Resistive Switching Time,  $t_{off}$

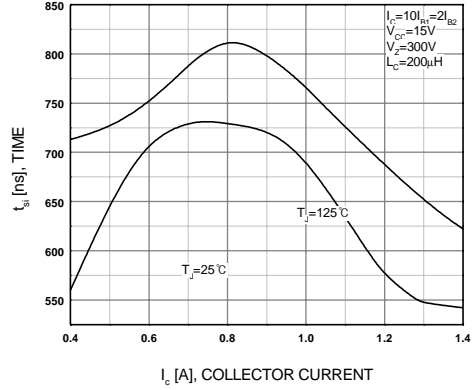


Figure 14. Inductive Switching Time,  $t_{si}$

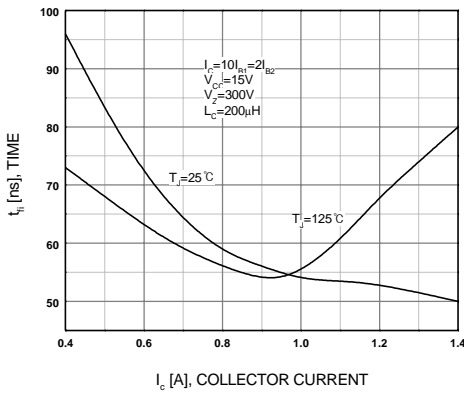


Figure 15. Inductive Switching Time,  $t_{fi}$

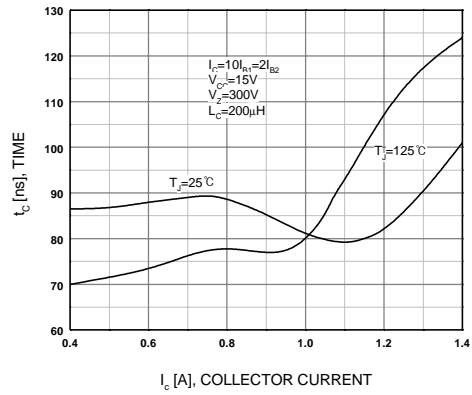


Figure 16. Inductive Switching Time,  $t_c$

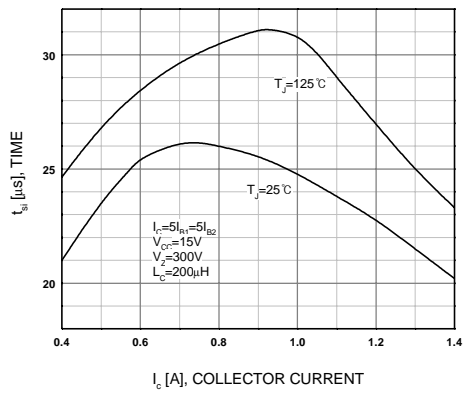


Figure 17. Inductive Switching Time,  $t_{si}$

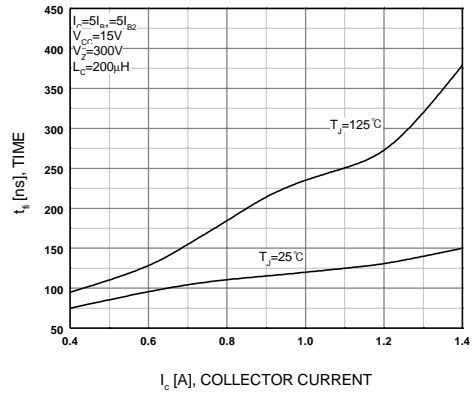


Figure 18. Inductive Switching Time,  $t_{fi}$

Typical Characteristics (Continued)

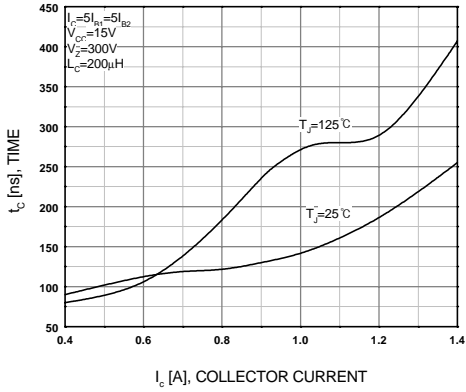


Figure 19. Inductive Switching Time,  $t_c$

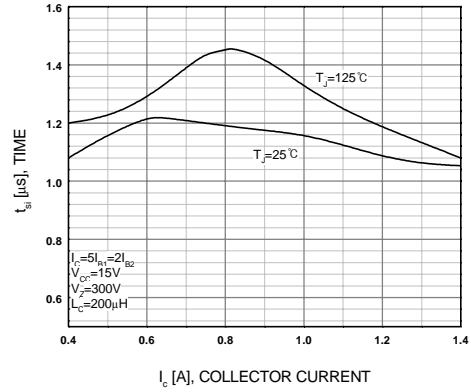


Figure 20. Inductive Switching Time,  $t_{si}$

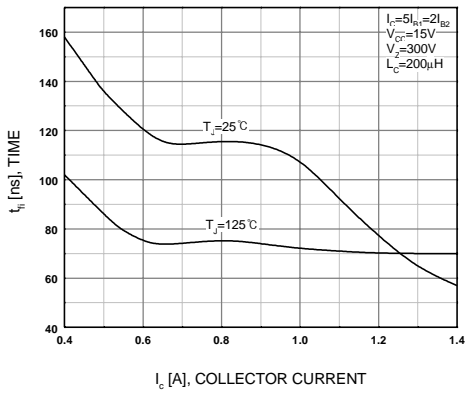


Figure 21. Inductive Switching Time,  $t_{fi}$

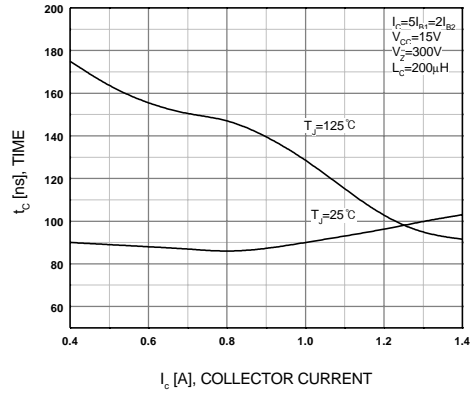


Figure 22. Inductive Switching Time,  $t_c$

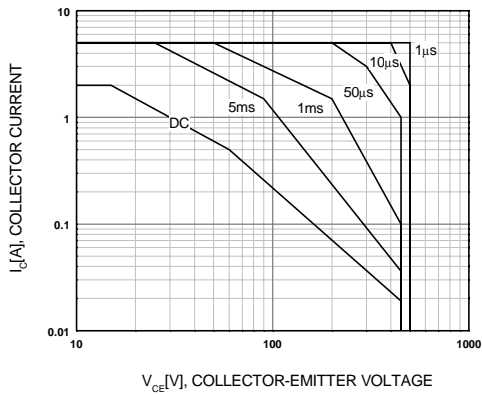


Figure 23. Forward Bias Safe Operating Area

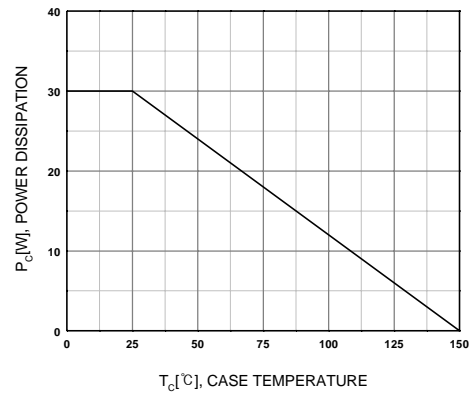
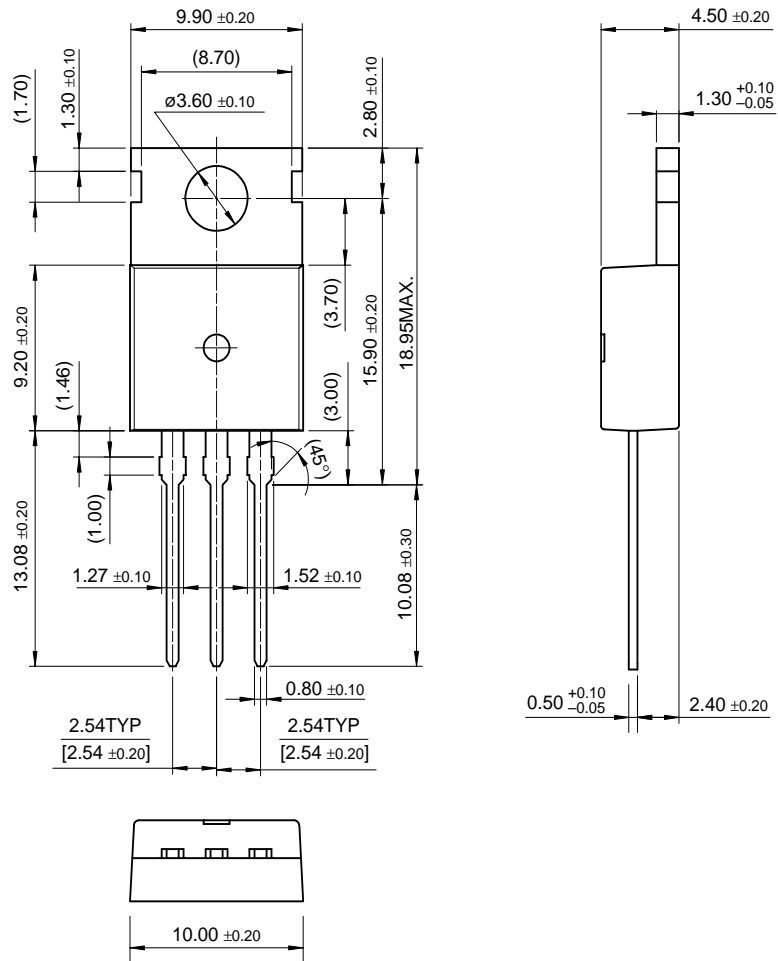


Figure 24. Power Derating

# Package Dimensions

## TO-220



Dimensions in Millimeters

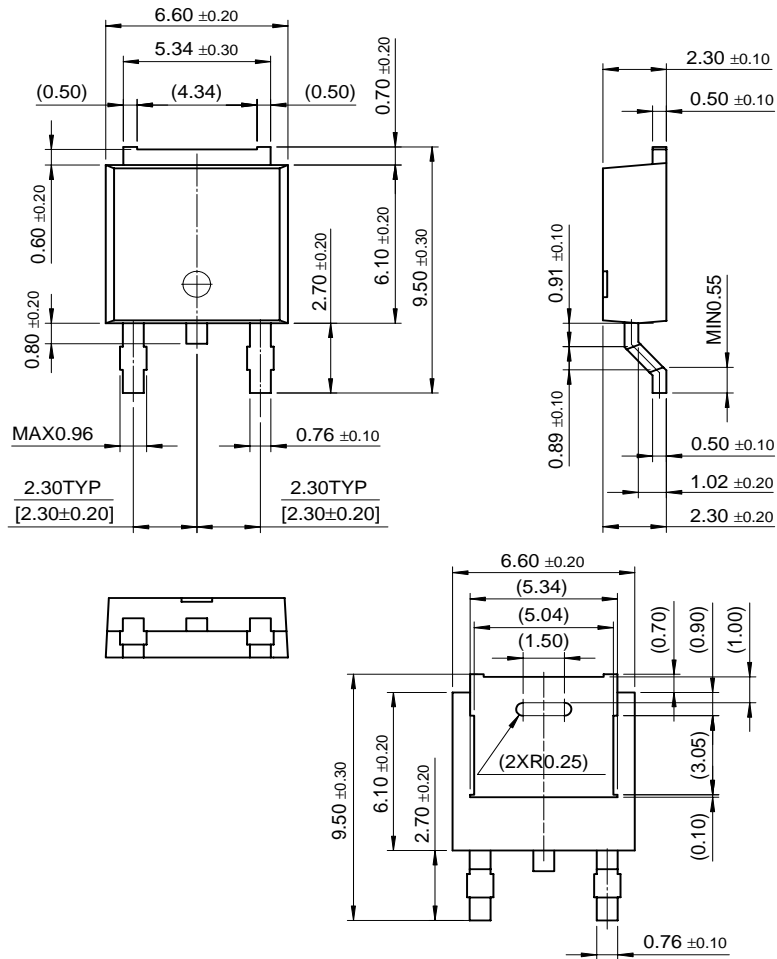
KSC5402D/KSC5402DT



# Package Dimensions (Continued)

KSC5402D/KSC5402DT

## D-PAK



Dimensions in Millimeters

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ActiveArray <sup>™</sup>	FACT Quiet series <sup>™</sup>	ISOPLANAR <sup>™</sup>	POP <sup>™</sup>	Stealth <sup>™</sup>
Bottomless <sup>™</sup>	FAST <sup>®</sup>	LittleFET <sup>™</sup>	Power247 <sup>™</sup>	SuperSOT <sup>™</sup> -3
CoolFET <sup>™</sup>	FAST <sup>™</sup>	MicroFET <sup>™</sup>	PowerTrench <sup>®</sup>	SuperSOT <sup>™</sup> -6
CROSSVOLT <sup>™</sup>	FRFET <sup>™</sup>	MicroPak <sup>™</sup>	QFET <sup>™</sup>	SuperSOT <sup>™</sup> -8
DOMET <sup>™</sup>	GlobalOptoisolator <sup>™</sup>	MICROWIRE <sup>™</sup>	QS <sup>™</sup>	SyncFET <sup>™</sup>
EcoSPARK <sup>™</sup>	GTO <sup>™</sup>	MSX <sup>™</sup>	QT Optoelectronics <sup>™</sup>	TinyLogic <sup>™</sup>
E <sup>2</sup> CMOS <sup>™</sup>	HiSeC <sup>™</sup>	MSXPro <sup>™</sup>	Quiet Series <sup>™</sup>	TruTranslation <sup>™</sup>
EnSigna <sup>™</sup>	I <sup>2</sup> C <sup>™</sup>	OCX <sup>™</sup>	RapidConfigure <sup>™</sup>	UHC <sup>™</sup>
Across the board. Around the world. <sup>™</sup>		OCXPro <sup>™</sup>	RapidConnect <sup>™</sup>	UltraFET <sup>®</sup>
The Power Franchise <sup>™</sup>		OPTOLOGIC <sup>®</sup>	SILENT SWITCHER <sup>®</sup>	VCX <sup>™</sup>
Programmable Active Droop <sup>™</sup>		OPTOPLANAR <sup>™</sup>	SMART START <sup>™</sup>	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

## PRODUCT STATUS DEFINITIONS

### Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.